2SK2922

Silicon N Channel MOS FET
UHF Power Amplifier

HITACHI

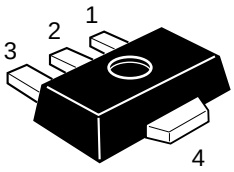
ADE-208-675(Z)
1st. Edition
Aug. 1998

Features

- High power output, High gain, High efficiency
  PG = 8.0dB, Pout = 31dBm, ηD = 57 %min. (f = 836.5MHz)
- Compact package capable of surface mounting

Outline

UPAK



1. Gate
2. Source
3. Drain
4. Source

This Device is sensitive to Electro Static Discharge.
An Adequate handling procedure is requested.

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	10	V
Gate to source voltage	V_{GSS}	±6	V
Drain current	I_D	0.7	A
Drain peak current	$I_{D(pulse)}$ Note1	1.4	A
Channel dissipation	Pch Note2	3	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–45 to +150	°C

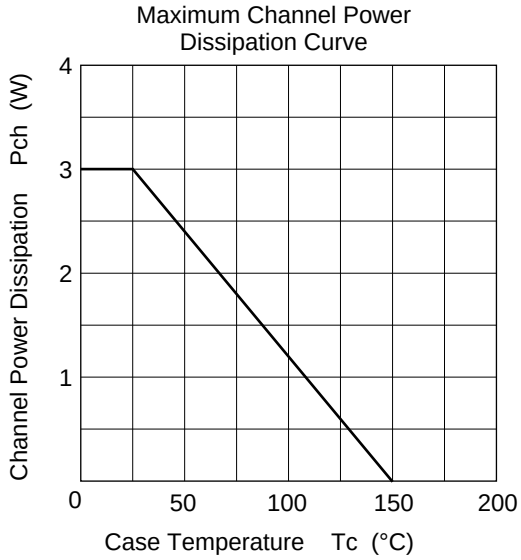
Note: 1. PW ≤ 10ms, duty cycle ≤ 50 %
2. Value at Tc = 25°C

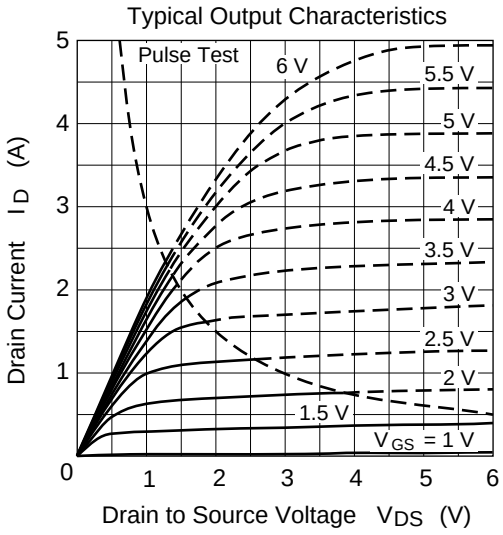
Electrical Characteristics (Ta = 25°C)

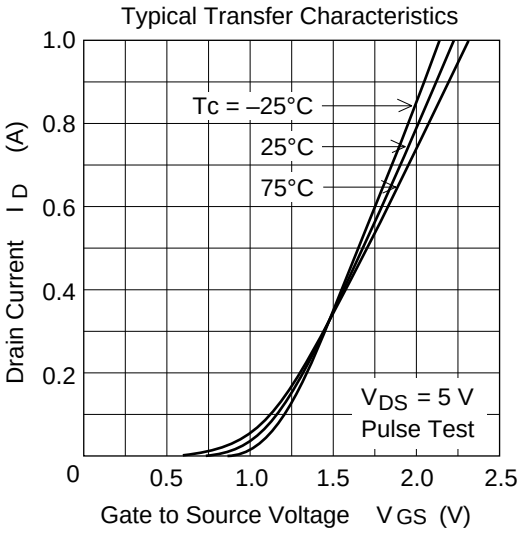
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Zero gate voltage drain current	I_{DSS}	—	—	100	µA	V_{DS} = 10 V, V_{GS} = 0
Gate to source leak current	I_{GSS}	—	—	±5.0	µA	V_{GS} = ±6V, V_{DS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	0.4	—	1.2	V	I_D = 3µA, V_{DS} = 5V
Input capacitance	Ciss	—	27	—	pF	V_{GS} = 2V, V_{DS} = 0, f = 1MHz
Output capacitance	Coss	—	13	—	pF	V_{DS} = 5, V_{GS} = 0, f = 1MHz
Output Power	Pout	31	—	—	dBm	V_{DS} = 4.7V, f =836.5MHz Pin = 23dBm
Drain Rational	ηD	57	—	—	%	V_{DS} = 4.7V, f =836.5MHz Pin = 23dBm

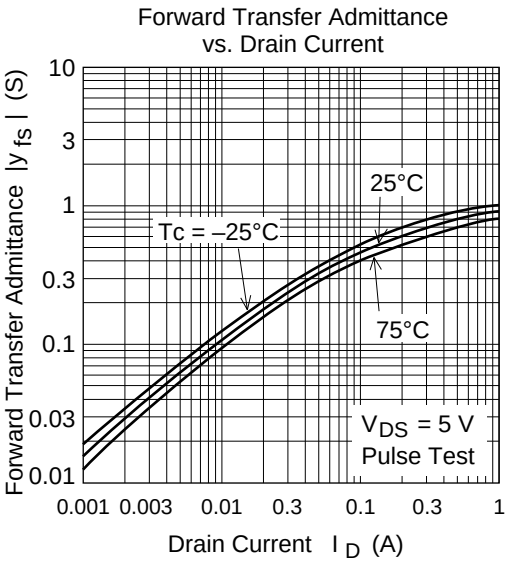
Note: 1. Marking is “HX”.

Main Characteristics

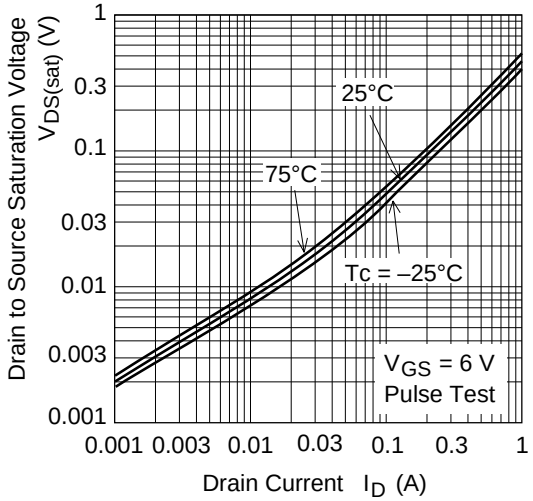




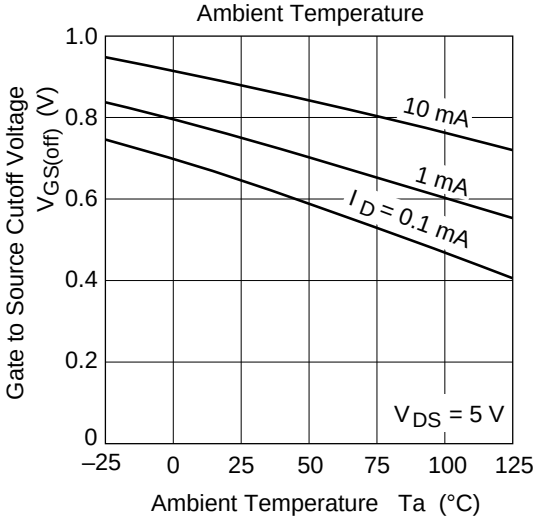




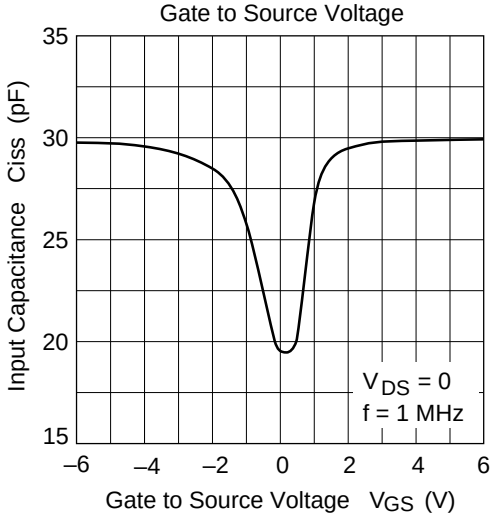
Drain to Source Saturation Voltage vs. Drain Current



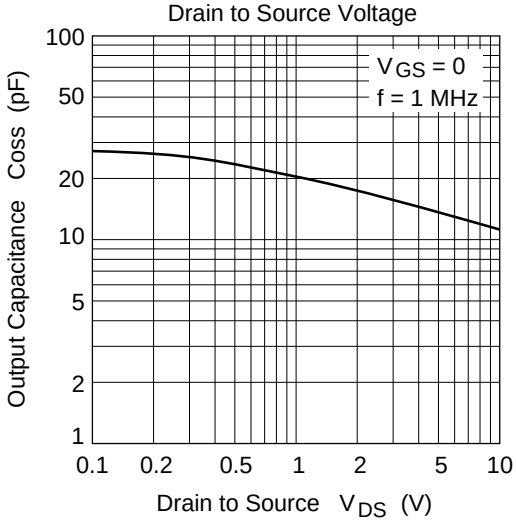
Gate to Source Cutoff Voltage vs. Ambient Temperature

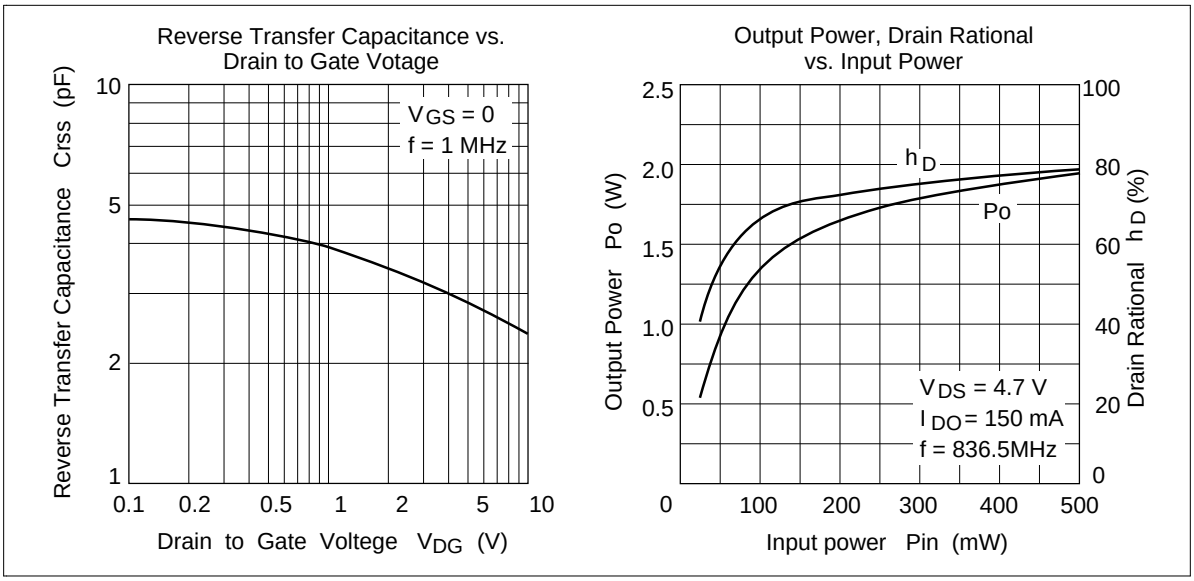


Input Capacitance vs. Gate to Source Voltage

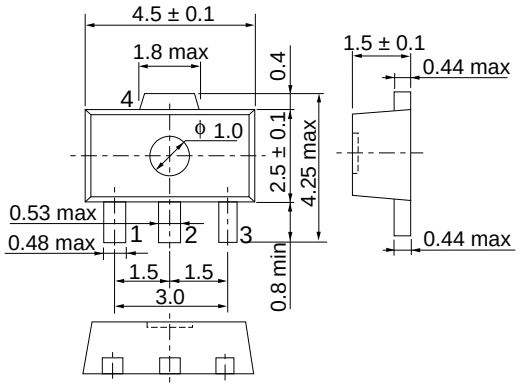


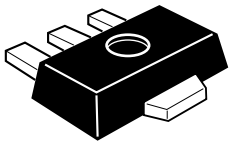
Output Capacitance vs. Drain to Source Voltage




Reverse Transfer Capacitance vs.
Drain to Gate Votage
Reverse Transfer Capacitance Crss (pF)
10
5
2
1
0.1
0.2
0.5
1
2
5
10
VGS = 0
f = 1 MHz
Drain to Gate Voltege VDG (V)
Output Power, Drain Rational
vs. Input Power
Output Power Po (W)
2.5
2.0
1.5
1.0
0.5
0
100
200
300
400
500
hD
Po
VDS = 4.7 V
IDO = 150 mA
f = 836.5MHz
Drain Rational hD (%)
100
80
60
40
20
0
Input power Pin (mW)

Package Dimensions **Unit: mm**





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